

- NOTES:
- MATERIAL:
HOUSING - POLYAMIDE (PA) GLASS FILLED, UL 94V-0, COLOR - BLACK
LATCH - POLYAMIDE (PA) GLASS FILLED, UL 94V-0, COLOR - BLACK
TERMINAL - COPPER ALLOY
 - FINISHES: TERMINAL PLATING SEE TABLE ON SHEET 5
 - PRODUCT SPECIFICATION: PS-78315-001
 - PACKAGING SPECIFICATION: PRODUCT SHALL BE PACKED IN TRAYS
 - CARD SLOT ACCEPTS 1.27 +/- 0.10MM MODULE THICKNESS (MEASURED FROM PC PADS)
 - MOLEX LOGO, DATE & PART NUMBERS INDICATED ON HOUSING
DATE CODE SHOULD BE INDICATE AS YYDDDX. 'X' WILL BE THE DIE NO.
 - MODULE SEATING PLANE FROM TOP OF PCB
 - KEEP OUT ZONE RESERVED FOR LATCH

UPT D/C W DIE NO	2015/01/20
EC NO: S2016-1099	2016/07/19
DRW:NCCTEH	2016/07/19
CHKD:CGTAN	2016/07/22
APPR:SHLENI	

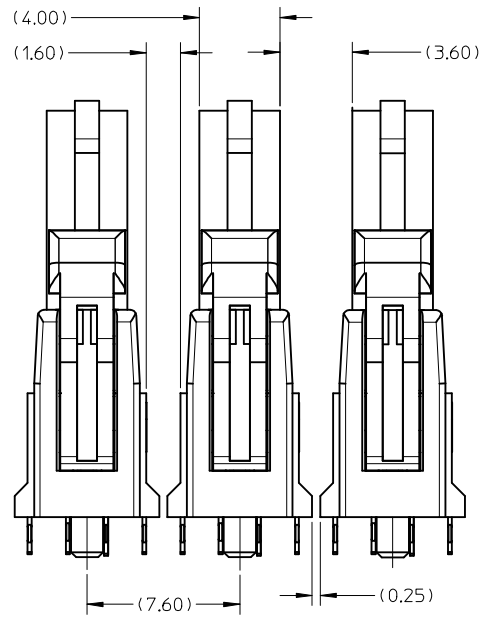
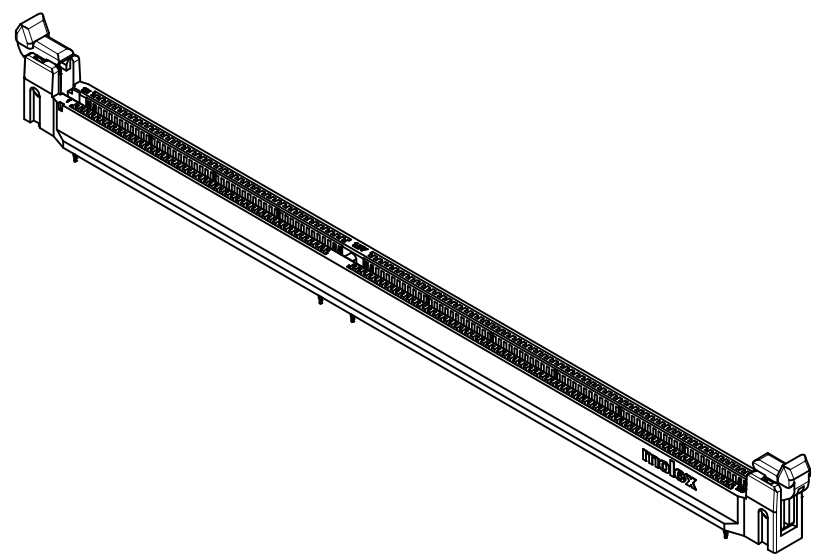
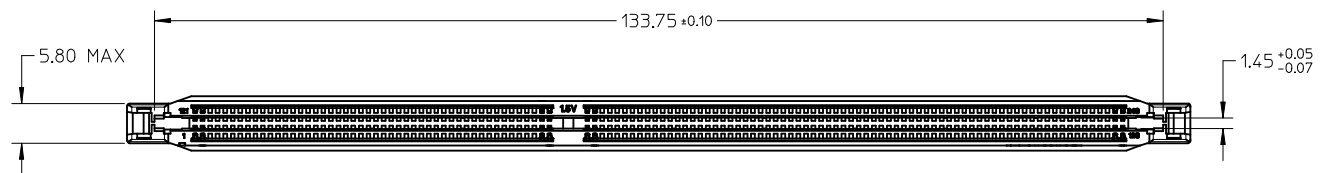
QUALITY SYMBOLS	DESCRIPTION
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$F_G=0$	
$F_B=0$	

GENERAL TOLERANCES (UNLESS SPECIFIED)	
	mm INCH
4 PLACES	± --- ± ---
3 PLACES	± --- ± ---
2 PLACES	± 0.20 ± ---
1 PLACE	± --- ± ---
0 PLACE	± --- ± ---
ANGULAR ± 1 °	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE MM ONLY	
DRAWN BY	DATE
CMTEO	2008/07/17
CHECKED BY	DATE
CCTEH	2008/07/30
APPROVED BY	DATE
SHLENI	2010/12/15
MATERIAL NO.	
SEE TABLE	

SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
TITLE		
DDR3 DIMM (LSP, VLP) 100MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR		
molex		
DOCUMENT NO.	SHEET NO.	
SD-78315-001	1 OF 6	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

10 9 8 7 6 5 4 3 2 1



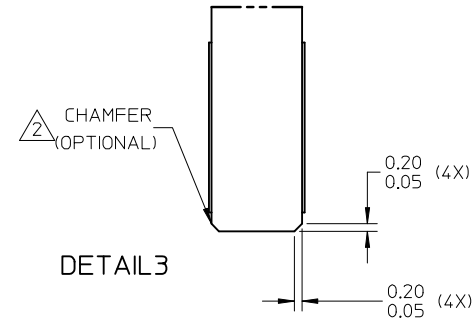
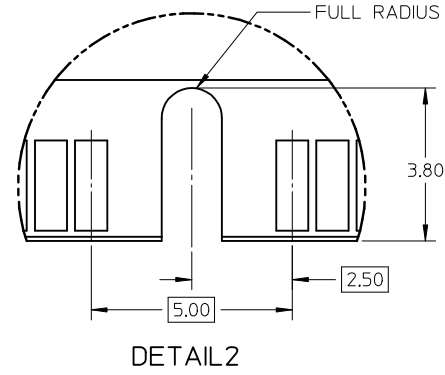
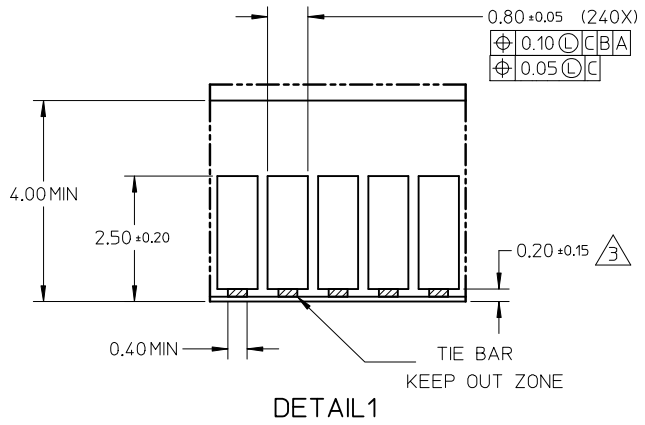
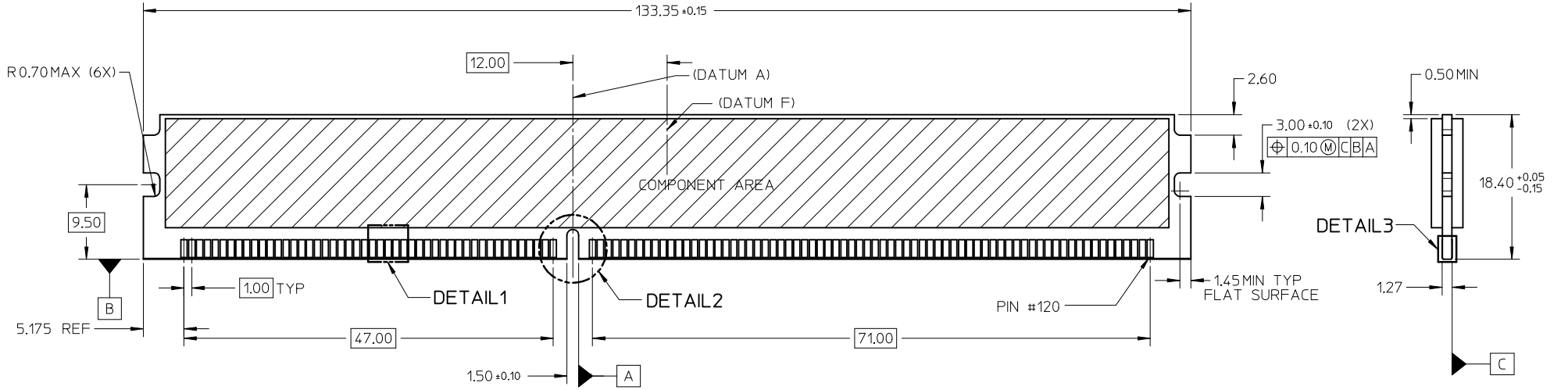
MINIMUM ROW TO ROW SPACING RECOMMENDATION
(USING 4.00MM MODULE CARD)

UPT D/C W DIE NO EC NO: S2016-1099 DRWN: CCTEH 2015/01/20 CHKD: CGTAN 2016/07/19 APPR: SHLENI 2016/07/22	QUALITY SYMBOLS $F_A=0$ $F_G=0$ $F_P=0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			mm	INCH	DRAWN BY CMTEO	DATE 2008/07/17	TITLE DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR			
		4 PLACES	± ---	± ---	CHECKED BY CCTEH	DATE 2008/07/30	molex DOCUMENT NO. SD-78315-001 SHEET NO. 2 OF 6			
		3 PLACES	± ---	± ---	APPROVED BY SHLENI	DATE 2010/12/15				
2 PLACES	± 0.20	± ---	MATERIAL NO.		SEE TABLE					
1 PLACE	± ---	± ---	ANGULAR ± 1 °		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
0 PLACE	± ---	± ---	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1

009MODULE CARD
 DDR3 DUAL INLINE MEMORY MODULE FAMILY 1.00 CONTACT CENTERS
 (JEDEC MO-269, ISSUE A, 12/05)



NOTES:

1. RECOMMENDED PLATING FOR CONTACT PADS:
 PREFERRED: 0.76 MICROMETERS GOLD PLATING MIN
 OVER 2.00 MICROMETERS NICKEL
 ALTERNATIVE: 0.05-0.75 MICROMETERS GOLD PLATING
 OVER 2.00 MICROMETERS NICKEL MUST
 USE AN ELECTRONIC CONTACT GRADE
 CORROSIVE BARRIER LUBRICANT

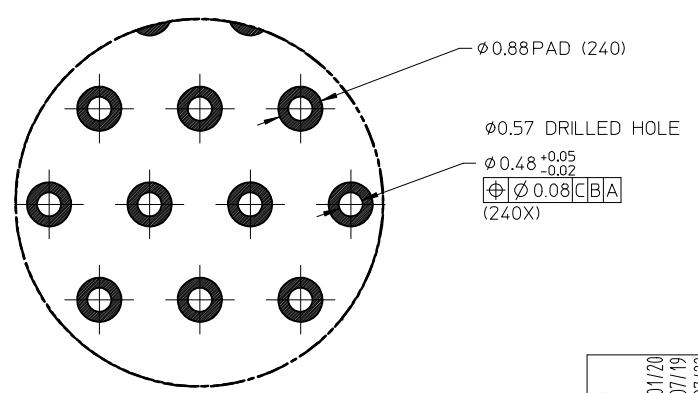
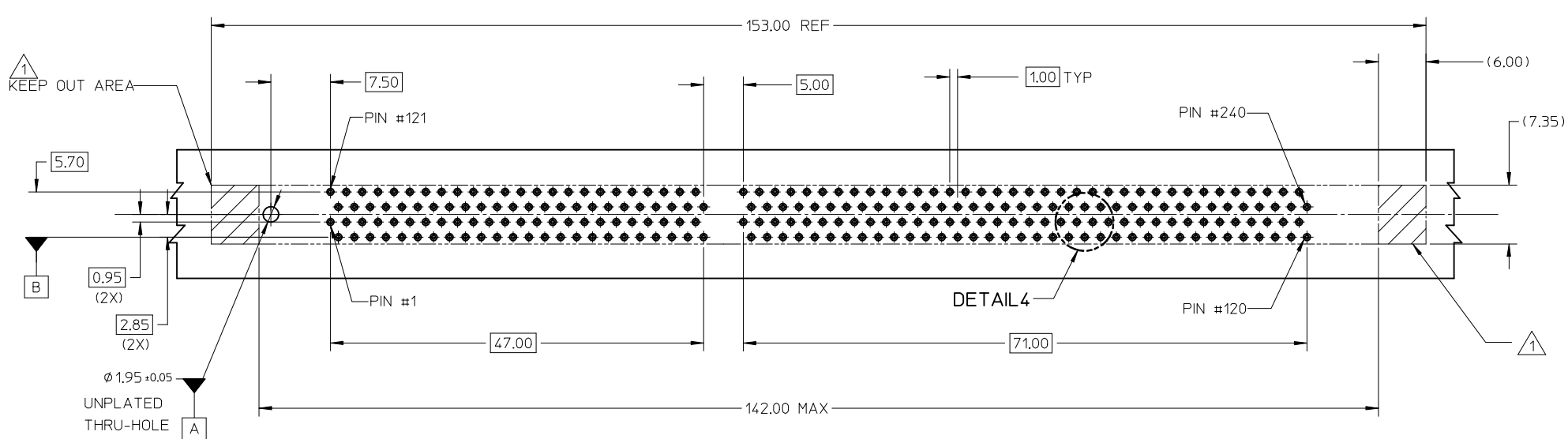
2. CHAMFER IS OPTIONAL AND IS NOT TO HIT THE GOLD PADS

3. LEADING EDGE OF GOLD PADS SPECIFIED BY KEEPOUT ZONE
 SHALL BE FREE OF BURRS AND EXTERNAL TIE BARS

UPT D/C W DIE NO A3	REV	DESCRIPTION 2015/01/20 2016/07/19 2016/07/22	QUALITY SYMBOLS FA=0 FG=0 FP=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
				mm	INCH	DRAWN BY CMTEO	DATE 2008/07/17	TITLE DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR			
				4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	CHECKED BY CCTEH	DATE 2008/07/30	molex			
				2 PLACES ± 0.20 ± ---	1 PLACE ± --- ± ---	APPROVED BY SHLENI	DATE 2010/12/15				
ANGULAR ± 1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-78315-001		SHEET NO. 3 OF 6			
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION											

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1



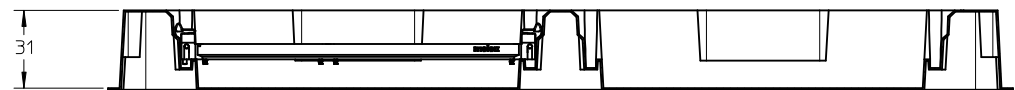
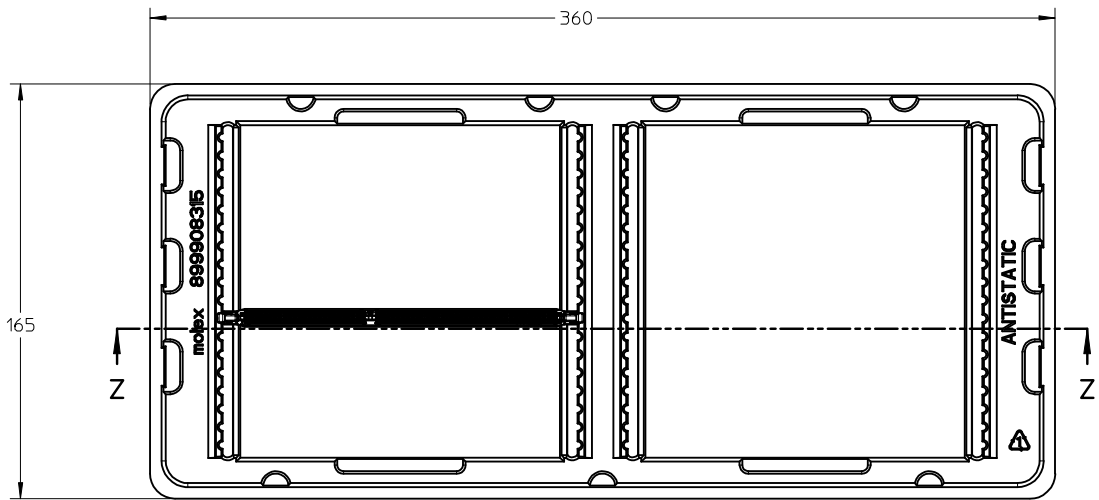
NOTES:
 1. KEEP OUT AREA IS THE AREA WHERE THE CONNECTOR (INCLUDING LATCH) IS MOUNTED ON THE PCB

UPT D/C W DIE NO EC NO: S2016-1099 DRWN: CCTEH 2015/01/20 CHYK: CGTAN 2016/07/19 APPR: SHLENI 2016/07/22	QUALITY SYMBOLS $F_A=0$ $F_G=0$ $F_P=0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			mm	INCH	DRAWN BY	DATE	TITLE			
		4 PLACES	± ---	± ---	CMTEO	2008/07/17	DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR			
		3 PLACES	± ---	± ---	CCTEH	2008/07/30				
2 PLACES	± 0.20	± ---	APPROVED BY		DATE	molex DOCUMENT NO. SD-78315-001 SHEET NO. 4 OF 6				
1 PLACE	± ---	± ---	SHLENI		2010/12/15					
0 PLACE	± ---	± ---	MATERIAL NO.		SEE TABLE					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			ANGULAR ± 1 °		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1

VIEW FOR PACKAGING TRAY



SECTION Z-Z

NOTE:
1. NO. OF CAVITY - 18 X 2 =36

UPT D/C W DIE NO EC NO: S2016-1099 DRW: CCTEH 2015/01/20 CHKD: CGTAN 2016/07/19 APPR: SHLENI 2016/07/22 REV A3	QUALITY SYMBOLS $\nabla_A = 0$ $\nabla_G = 0$ $\nabla_F = 0$	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± --- ± --- 0 PLACE ± --- ± --- ANGULAR ± 1 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DIMENSION STYLE MM ONLY DRAWN BY: CMTEO CHECKED BY: CCTEH APPROVED BY: SHLENI DATE: 2008/07/17 DATE: 2008/07/30 DATE: 2010/12/15	SCALE NTS TITLE DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR molex SD-78315-001	DESIGN UNITS METRIC THIRD ANGLE PROJECTION	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-78315-001	SHEET NO. 5 OF 6
	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							
	SIZE A3							
	DIMENSION STYLE MM ONLY							

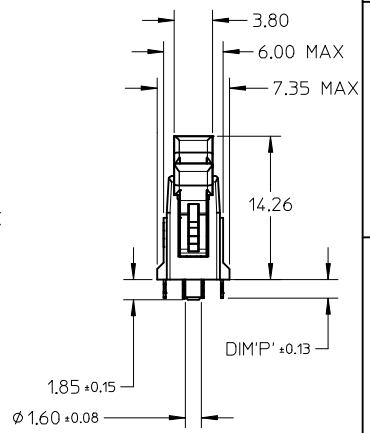
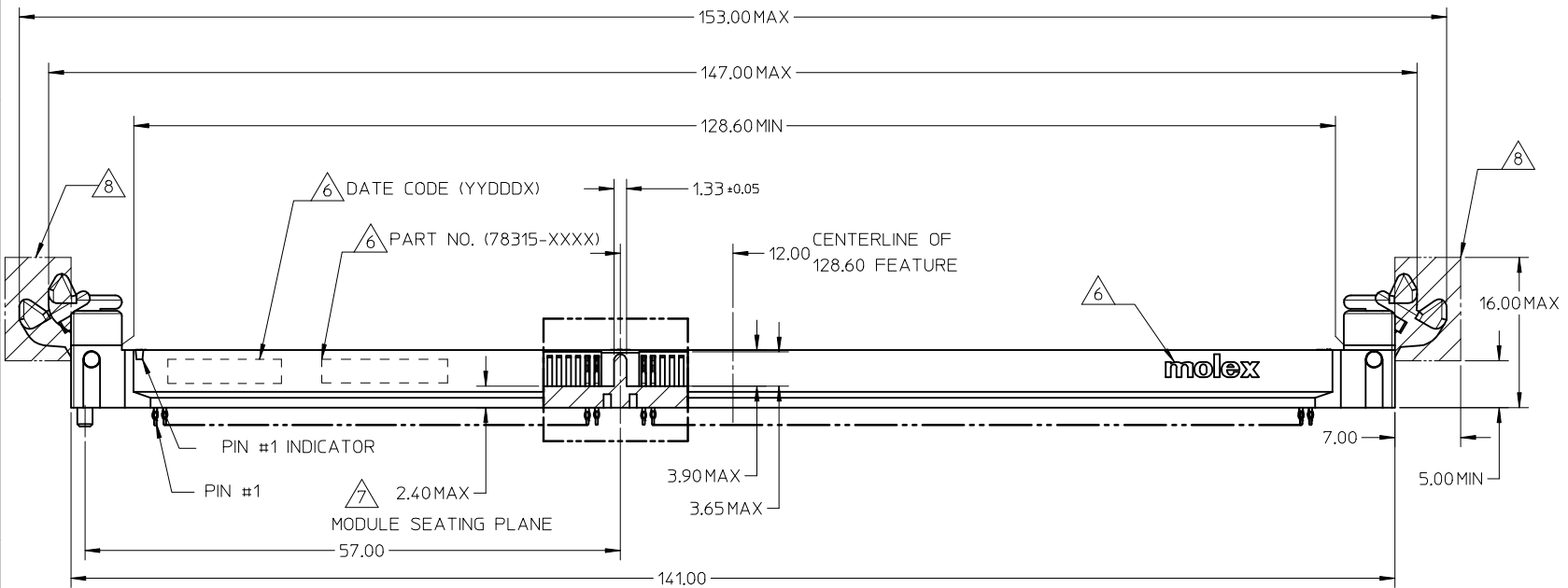
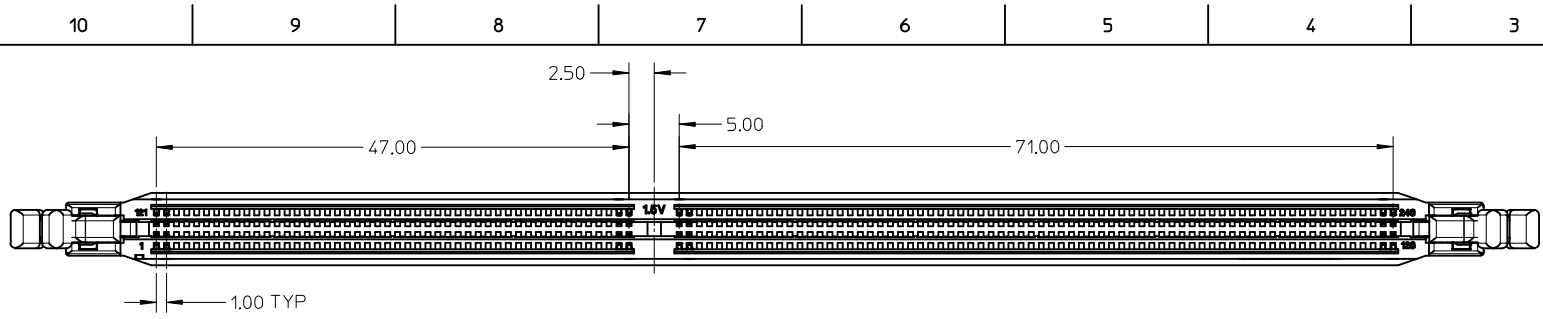
9 8 7 6 5 4 3 2 1

10 | 9 | 8 | 7 | 6 | 5 | 4 | 3 | 2 | 1

PART NO.	KEY POS.	DIM 'P'	RECOMMENDED PCB THICKNESS	PLATING OPTION		LATCH COLOUR	HOUSING COLOUR
				CONTACT AREA	TAIL AREA		
78315-0001	CENTER (1.5V)	1.85	2.40	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	0.38 TO 1.52 MICROMETER/15 TO 60 MICROINCH MIN TIN (MATT) OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	BLACK	BLACK
78315-0051						BLUE	BLUE
78315-0011		2.85	2.60			BLACK	BLACK

UPT D/C W DIE NO EC NO: S2016-1099 DRWN: CTEH CHKD: CGTAN APPR: SHLENI 2015/01/20 2016/07/19 2016/07/22	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	$F_A=0$ $F_G=0$ $F_P=0$	mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± --- ± --- 0 PLACE ± --- ± ---	MM ONLY	NTS	METRIC	
	DESCRIPTION	DRAWN BY: CMTEO DATE: 2008/07/17 CHECKED BY: CTEH DATE: 2008/07/30 APPROVED BY: SHLENI DATE: 2010/12/15	TITLE	DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR		
	REV	ANGULAR ± 1 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO.	DOCUMENT NO.		
	A3	SEE TABLE	SD-78315-001	SHEET NO. 6 OF 6		

9 | 8 | 7 | 6 | 5 | 4 | 3 | 2 | 1



- NOTES:
- MATERIAL:
HOUSING - POLYAMIDE (PA) GLASS FILLED, UL 94V-0, COLOR - BLACK
LATCH - POLYAMIDE (PA) GLASS FILLED, UL 94V-0, COLOR - BLACK
TERMINAL - COPPER ALLOY
 - FINISHES: TERMINAL PLATING SEE TABLE ON SHEET 5
 - PRODUCT SPECIFICATION: PS-78315-001
 - PACKAGING SPECIFICATION: PRODUCT SHALL BE PACKED IN TRAYS
 - CARD SLOT ACCEPTS 1.27 +/- 0.10MM MODULE THICKNESS (MEASURED FROM PC PADS)
 - MOLEX LOGO, DATE & PART NUMBERS INDICATED ON HOUSING
DATE CODE SHOULD BE INDICATE AS YYDDDX. 'X' WILL BE THE DIE NO.
 - MODULE SEATING PLANE FROM TOP OF PCB
 - KEEP OUT ZONE RESERVED FOR LATCH

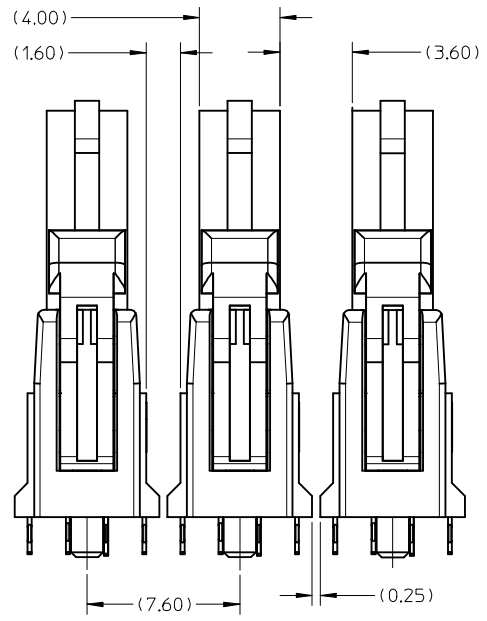
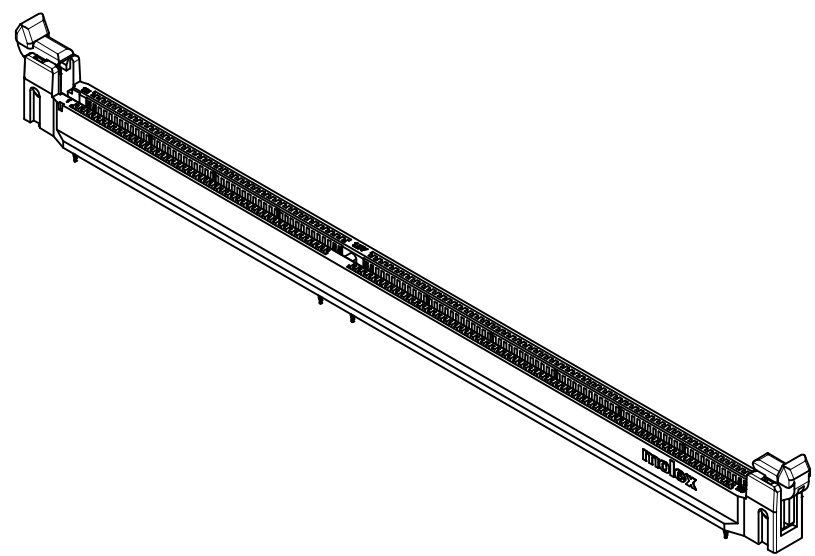
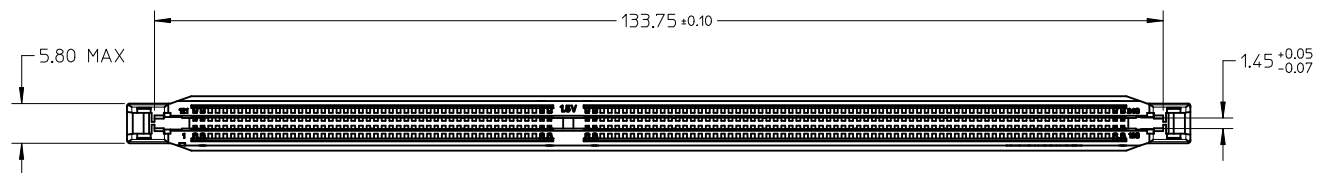
UPT D/C W DIE NO	2015/01/20	2016/07/19	2016/07/22
EC NO: S2016-1099	DRW:NCCTEH	CHKD:CGTAN	APPR:SHLENI
A3	REV	DESCRIPTION	QUALITY SYMBOLS

GENERAL TOLERANCES (UNLESS SPECIFIED)	
	mm INCH
4 PLACES	± --- ± ---
3 PLACES	± --- ± ---
2 PLACES	± 0.20 ± ---
1 PLACE	± --- ± ---
0 PLACE	± --- ± ---
ANGULAR ± 1 °	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE MM ONLY	
DRAWN BY	DATE
CMTEO	2008/07/17
CHECKED BY	DATE
CCTEH	2008/07/30
APPROVED BY	DATE
SHLENI	2010/12/15
MATERIAL NO.	
SEE TABLE	
SIZE	A3

SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
TITLE		
DDR3 DIMM (LSP, VLP) 100MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR		
molex		
DOCUMENT NO.	SHEET NO.	
SD-78315-001	1 OF 6	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

10 9 8 7 6 5 4 3 2 1



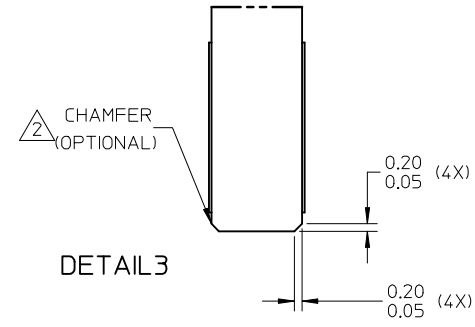
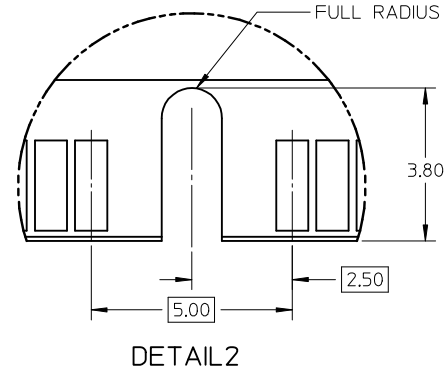
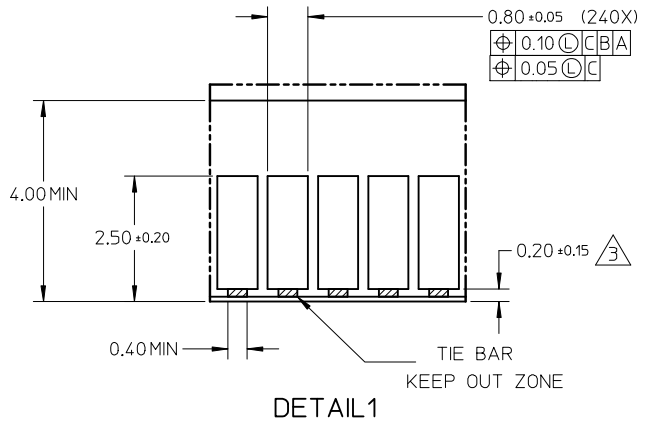
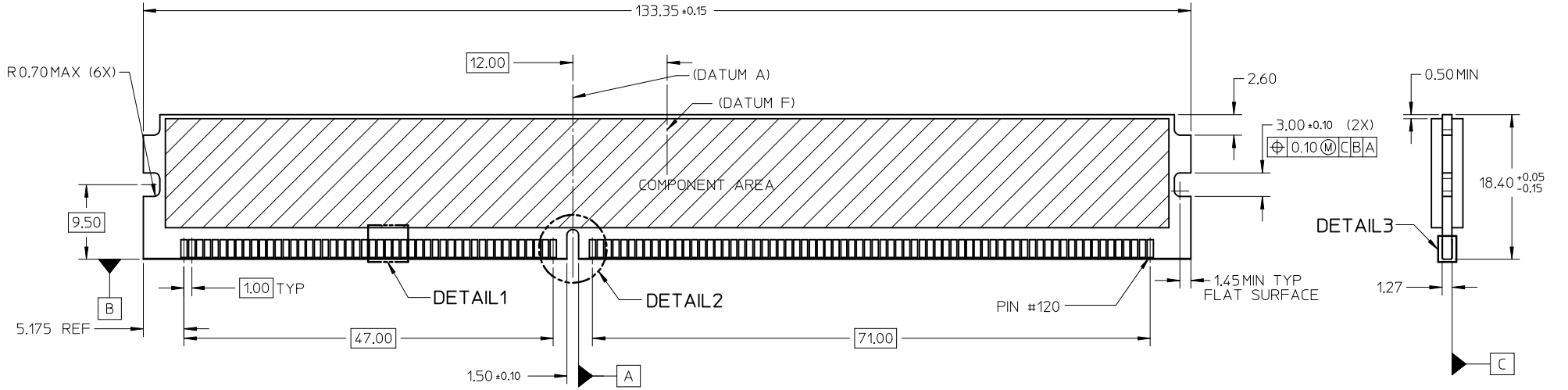
MINIMUM ROW TO ROW SPACING RECOMMENDATION
(USING 4.00MM MODULE CARD)

UPT D/C W DIE NO EC NO: S2016-1099 DRWN: CCTEH 2015/01/20 CHKD: CGTAN 2016/07/19 APPR: SHLENI 2016/07/22	QUALITY SYMBOLS $F_A = 0$ $F_G = 0$ $F_P = 0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			mm	INCH	DRAWN BY	DATE	TITLE			
		4 PLACES	± ---	± ---	CMTEO	2008/07/17	DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR molex DOCUMENT NO. SD-78315-001 SHEET NO. 2 OF 6			
		3 PLACES	± ---	± ---	CHECKED BY	DATE				
2 PLACES	± 0.20	± ---	CCTEH	2008/07/30						
1 PLACE	± ---	± ---	APPROVED BY	DATE						
0 PLACE	± ---	± ---	SHLENI	2010/12/15	MATERIAL NO.		SEE TABLE			
ANGULAR ± 1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1

009MODULE CARD
 DDR3 DUAL INLINE MEMORY MODULE FAMILY 1.00 CONTACT CENTERS
 (JEDEC MO-269, ISSUE A, 12/05)



NOTES:

1. RECOMMENDED PLATING FOR CONTACT PADS:
 PREFERRED: 0.76 MICROMETERS GOLD PLATING MIN
 OVER 2.00 MICROMETERS NICKEL
 ALTERNATIVE: 0.05-0.75 MICROMETERS GOLD PLATING
 OVER 2.00 MICROMETERS NICKEL MUST
 USE AN ELECTRONIC CONTACT GRADE
 CORROSIVE BARRIER LUBRICANT

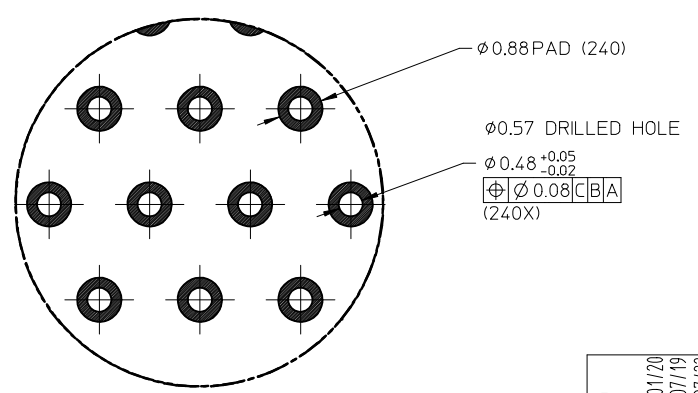
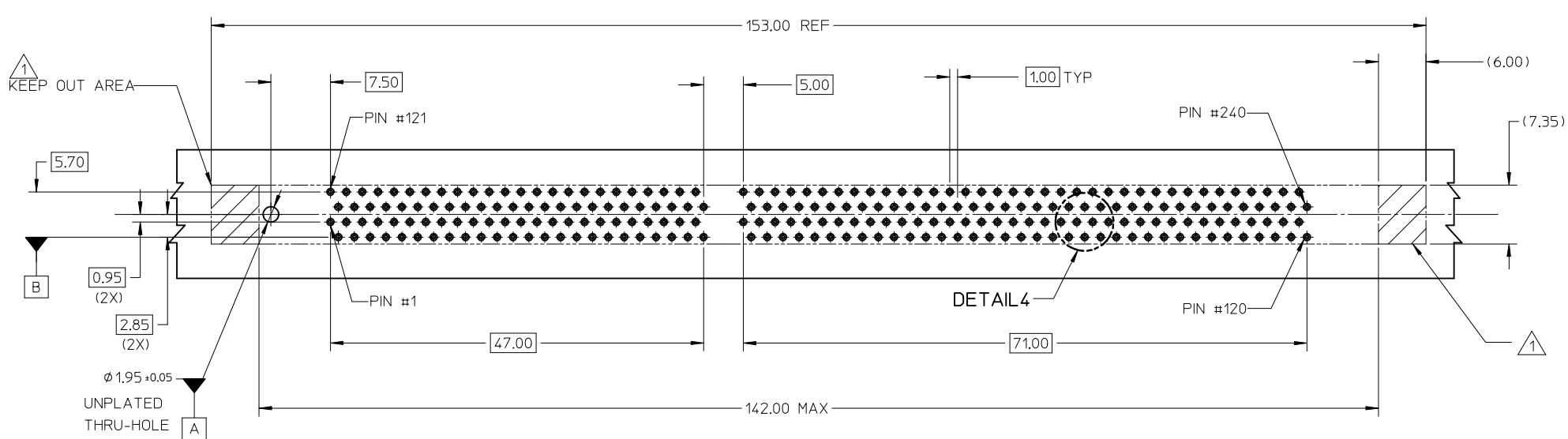
2. CHAMFER IS OPTIONAL AND IS NOT TO HIT THE GOLD PADS

3. LEADING EDGE OF GOLD PADS SPECIFIED BY KEEPOUT ZONE
 SHALL BE FREE OF BURRS AND EXTERNAL TIE BARS

UPT D/C W DIE NO A3	REV	DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
						MM ONLY		NTS	METRIC		
					mm	INCH	DRAWN BY	DATE	TITLE		
				4 PLACES	± ---	± ---	CMTEO	2008/07/17	DDR3 DIMM (LSP, VLP)		
					1.00MM PITCH, 240 CKTS						
									VERTICAL P/F, LOWLLCR		
									molex		
									DOCUMENT NO.	SHEET NO.	
									SD-78315-001	3 OF 6	
									THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1



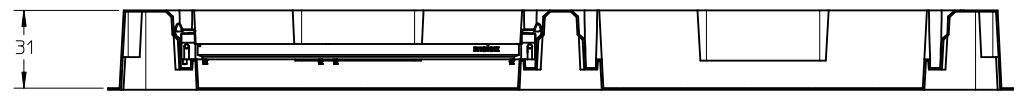
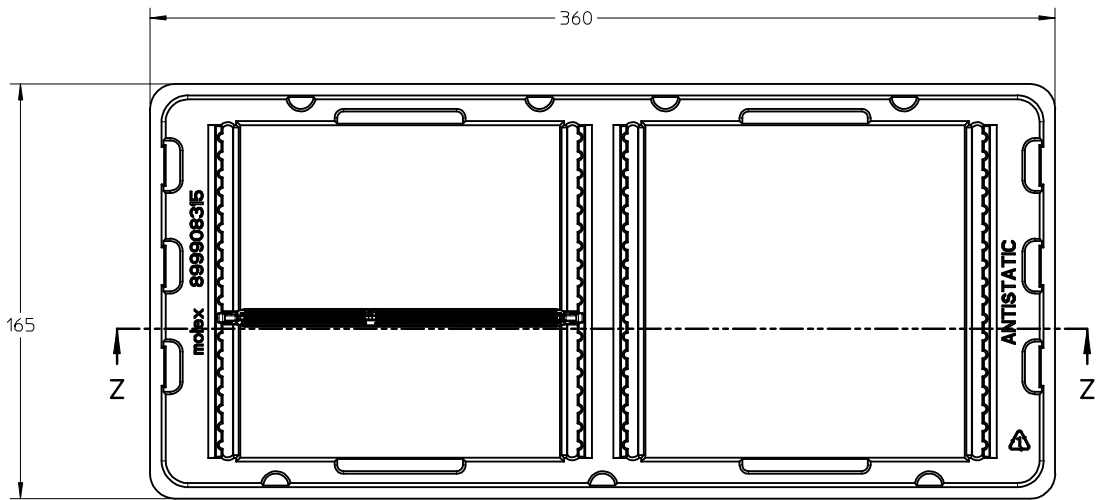
NOTES:
 1. KEEP OUT AREA IS THE AREA WHERE THE CONNECTOR (INCLUDING LATCH) IS MOUNTED ON THE PCB

UPT D/C W DIE NO EC NO: S2016-1099 DRWN: CCTEH 2015/01/20 CHYK: CGTAN 2016/07/19 APPR: SHLENI 2016/07/22	QUALITY SYMBOLS $F_A=0$ $F_G=0$ $F_P=0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			mm	INCH	DRAWN BY	DATE	TITLE			
		4 PLACES	± ---	± ---	CMTEO	2008/07/17	DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR			
		3 PLACES	± ---	± ---	CCTEH	2008/07/30				
2 PLACES	± 0.20	± ---	APPROVED BY		DATE	molex SD-78315-001				
1 PLACE	± ---	± ---	SHLENI		2010/12/15					
0 PLACE	± ---	± ---	MATERIAL NO.		DATE	DOCUMENT NO.		SHEET NO.		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			ANGULAR ± 1 °		SEE TABLE		SD-78315-001		4 OF 6	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION										

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1

VIEW FOR PACKAGING TRAY



SECTION Z-Z

NOTE:
1. NO. OF CAVITY - 18 X 2 =36

UPT D/C W DIE NO EC NO: S2016-1099 DRW: CCTEH CHKD: CGTAN APPR: SHLENI 2015/01/20 2016/07/19 2016/07/22	QUALITY SYMBOLS $\nabla_A = 0$ $\nabla_G = 0$ $\nabla_F = 0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	2 PLACES ± 0.20 ± ---	1 PLACE ± --- ± ---	0 PLACE ± --- ± ---	DRAWN BY CMTEO	DATE 2008/07/17	TITLE DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR
		ANGULAR ± 1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		CHECKED BY CCTEH	DATE 2008/07/30	APPROVED BY SHLENI	DATE 2010/12/15
		MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-78315-001		SHEET NO. 5 OF 6		molex	

9 8 7 6 5 4 3 2 1

10 | 9 | 8 | 7 | 6 | 5 | 4 | 3 | 2 | 1

PART NO.	KEY POS.	DIM 'P'	RECOMMENDED PCB THICKNESS	PLATING OPTION		LATCH COLOUR	HOUSING COLOUR
				CONTACT AREA	TAIL AREA		
78315-0001	CENTER (1.5V)	1.85	2.40	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	0.38 TO 1.52 MICROMETER/15 TO 60 MICROINCH MIN TIN (MATT) OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	BLACK	BLACK
78315-0051						BLUE	BLUE
78315-0011		2.85	2.60			BLACK	BLACK

UPT D/C W DIE NO EC NO: S2016-1099 DRWN: CTEH CHKD: CGTAN APPR: SHLENI 2015/01/20 2016/07/19 2016/07/22	QUALITY SYMBOLS $F_A=0$ $F_G=0$ $F_P=0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			mm	INCH	DRAWN BY CMTEO	DATE 2008/07/17	TITLE DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR molex DOCUMENT NO. SD-78315-001 SHEET NO. 6 OF 6		
		4 PLACES	± ---	± ---	CHECKED BY CCTEH	DATE 2008/07/30			
		3 PLACES	± ---	± ---	APPROVED BY SHLENI	DATE 2010/12/15			
2 PLACES	± 0.20	± ---	MATERIAL NO. SEE TABLE						
1 PLACE	± ---	± ---	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
0 PLACE	± ---	± ---	ANGULAR ± 1 °						

9 | 8 | 7 | 6 | 5 | 4 | 3 | 2 | 1